



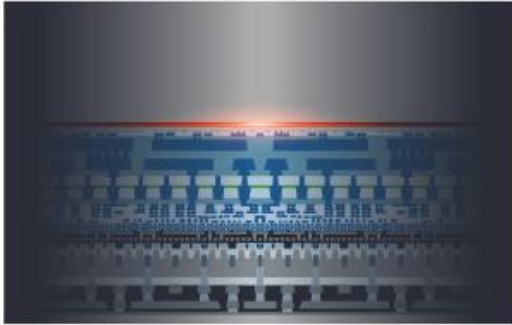
Wafer Bonding and NanoCleave: The New Lithography Scaling – March 17, 2023



Will the Green Shoots Be Damaged by a Long Winter?

“Green shoots” refers to signs of economic recovery. As a former analyst, I always found forecasting for the next year in December to be the biggest challenge, and perhaps the biggest miss of the year. You essentially are working without a net. Historically calendar Q4 revenue estimates by the equipment companies are positive, as the semiconductor manufacturers are spending the last of their budgets.

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Wafer Bonding and NanoCleave: The New Lithography Scaling

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EV Group (EVG) is a leading supplier of equipment and process solutions for the manufacture of semiconductors, microelectromechanical systems (MEMS), compound semiconductors, power devices, and nanotechnology devices. Key products include wafer bonding, thin-wafer processing, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners, and inspection systems. [Congratulations](#) to EVG for being named this year's 3D InCites recipient of Process of the Year for its NanoCleave, a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory, and power device formation, as well as advanced packaging. It is a fully front-end-compatible layer release technology featuring an IR laser that can pass through silicon. Coupled with the use of specially formulated inorganic layers, this technology enables an IR laser-initiated release of any ultra-thin film or layer from silicon carriers with nanometer precision. NanoCleave enables silicon wafer carriers in advanced packaging processes such as FOWLP using mold/reconstituted wafers and interposers for 3D-SICs.

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